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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	32
Number of Logic Elements/Cells	256
Total RAM Bits	-
Number of I/O	78
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo256c-4t100c

Features

■ Non-volatile, Infinitely Reconfigurable

- Instant-on – powers up in microseconds
- Single chip, no external configuration memory required
- Excellent design security, no bit stream to intercept
- Reconfigure SRAM based logic in milliseconds
- SRAM and non-volatile memory programmable through JTAG port
- Supports background programming of non-volatile memory

■ Sleep Mode

- Allows up to 100x static current reduction

■ TransFR™ Reconfiguration (TFR)

- In-field logic update while system operates

■ High I/O to Logic Density

- 256 to 2280 LUT4s
- 73 to 271 I/Os with extensive package options
- Density migration supported
- Lead free/RoHS compliant packaging

■ Embedded and Distributed Memory

- Up to 27.6 Kbits sysMEM™ Embedded Block RAM
- Up to 7.7 Kbits distributed RAM
- Dedicated FIFO control logic

■ Flexible I/O Buffer

- Programmable sysIO™ buffer supports wide range of interfaces:
 - LVCMOS 3.3/2.5/1.8/1.5/1.2
 - LVTTTL
 - PCI
 - LVDS, Bus-LVDS, LVPECL, RSDS

■ sysCLOCK™ PLLs

- Up to two analog PLLs per device
- Clock multiply, divide, and phase shifting

■ System Level Support

- IEEE Standard 1149.1 Boundary Scan
- Onboard oscillator
- Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply
- IEEE 1532 compliant in-system programming

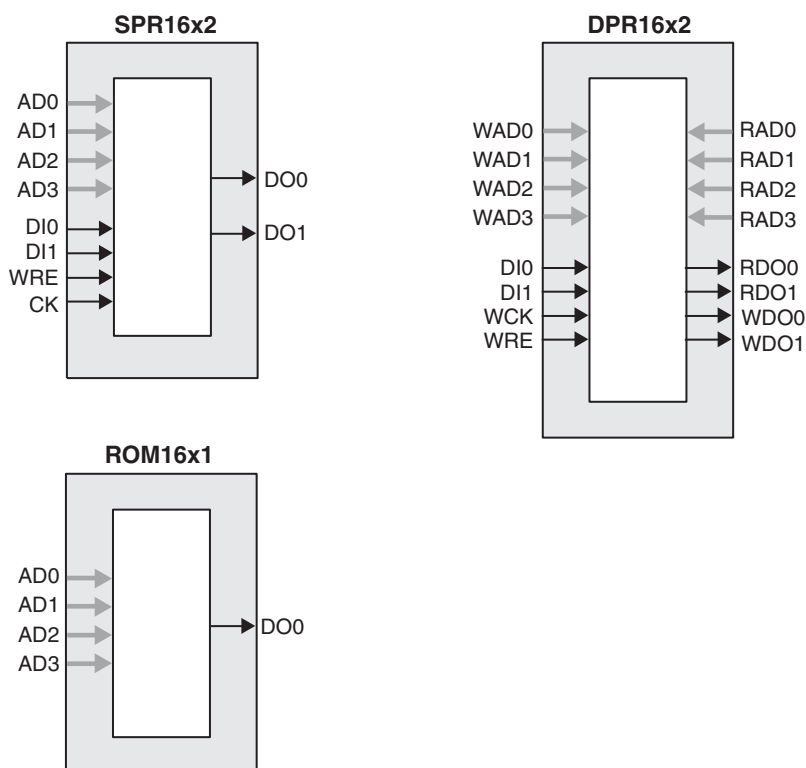
Introduction

The MachXO is optimized to meet the requirements of applications traditionally addressed by CPLDs and low capacity FPGAs: glue logic, bus bridging, bus interfacing, power-up control, and control logic. These devices bring together the best features of CPLD and FPGA devices on a single chip.

Table 1-1. MachXO Family Selection Guide

Device	LCMX0256	LCMX0640	LCMX01200	LCMX02280
LUTs	256	640	1200	2280
Dist. RAM (Kbits)	2.0	6.1	6.4	7.7
EBR SRAM (Kbits)	0	0	9.2	27.6
Number of EBR SRAM Blocks (9 Kbits)	0	0	1	3
V _{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
Number of PLLs	0	0	1	2
Max. I/O	78	159	211	271
Packages				
100-pin TQFP (14x14 mm)	78	74	73	73
144-pin TQFP (20x20 mm)		113	113	113
100-ball csBGA (8x8 mm)	78	74		
132-ball csBGA (8x8 mm)		101	101	101
256-ball caBGA (14x14 mm)		159	211	211
256-ball ftBGA (17x17 mm)		159	211	211
324-ball ftBGA (19x19 mm)				271

Figure 2-6. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Table 2-4. PFU Modes of Operation

Logic	Ripple	RAM	ROM
LUT 4x8 or MUX 2x1 x 8	2-bit Add x 4	SPR16x2 x 4 DPR16x2 x 2	ROM16x1 x 8
LUT 5x4 or MUX 4x1 x 4	2-bit Sub x 4	SPR16x4 x 2 DPR16x4 x 1	ROM16x2 x 4
LUT 6x2 or MUX 8x1 x 2	2-bit Counter x 4	SPR16x8 x 1	ROM16x4 x 2
LUT 7x1 or MUX 16x1 x 1	2-bit Comp x 4		ROM16x8 x 1

Routing

There are many resources provided in the MachXO devices to route signals individually or as buses with related control signals. The routing resources consist of switching circuitry, buffers and metal interconnect (routing) segments.

The inter-PFU connections are made with three different types of routing resources: x1 (spans two PFUs), x2 (spans three PFUs) and x6 (spans seven PFUs). The x1, x2, and x6 connections provide fast and efficient connections in the horizontal and vertical directions.

Table 2-5. PLL Signal Descriptions

Signal	I/O	Description
CLKI	I	Clock input from external pin or routing
CLKFB	I	PLL feedback input from PLL output, clock net, routing/external pin or internal feedback from CLKINTFB port
RST	I	"1" to reset the input clock divider
CLKOS	O	PLL output clock to clock tree (phase shifted/duty cycle changed)
CLKOP	O	PLL output clock to clock tree (No phase shift)
CLKOK	O	PLL output to clock tree through secondary clock divider
LOCK	O	"1" indicates PLL LOCK to CLKI
CLKINTFB	O	Internal feedback source, CLKOP divider output before CLOCKTREE
DDAMODE	I	Dynamic Delay Enable. "1": Pin control (dynamic), "0": Fuse Control (static)
DDAIZR	I	Dynamic Delay Zero. "1": delay = 0, "0": delay = on
DDAILAG	I	Dynamic Delay Lag/Lead. "1": Lag, "0": Lead
DDAIDEL[2:0]	I	Dynamic Delay Input

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

sysMEM Memory

The MachXO1200 and MachXO2280 devices contain sysMEM Embedded Block RAMs (EBRs). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

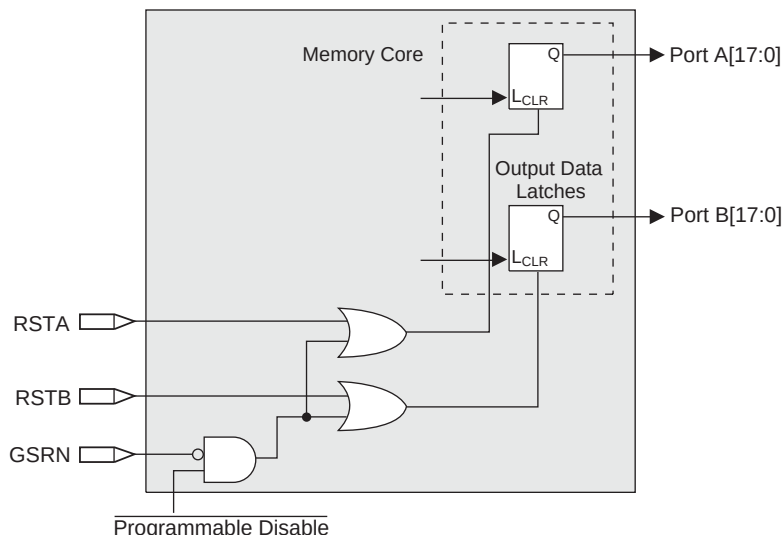
sysMEM Memory Block

The sysMEM block can implement single port, dual port, pseudo dual port, or FIFO memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Table 2-6. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
True Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18
Pseudo Dual Port	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36
FIFO	8,192 x 1 4,096 x 2 2,048 x 4 1,024 x 9 512 x 18 256 x 36

Figure 2-13. Memory Core Reset

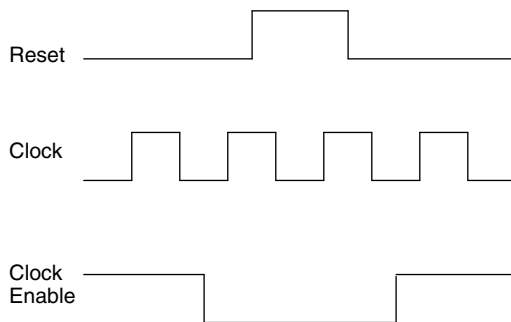


For further information on the sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-14. The GSR input to the EBR is always asynchronous.

Figure 2-14. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EBR RAM, ROM and FIFO implementations. For the EBR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-14. The reset timing rules apply to the RPRreset input vs the RE input and the RST input vs. the WE and RE inputs. Both RST and RPRreset are always asynchronous EBR inputs.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O

When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)

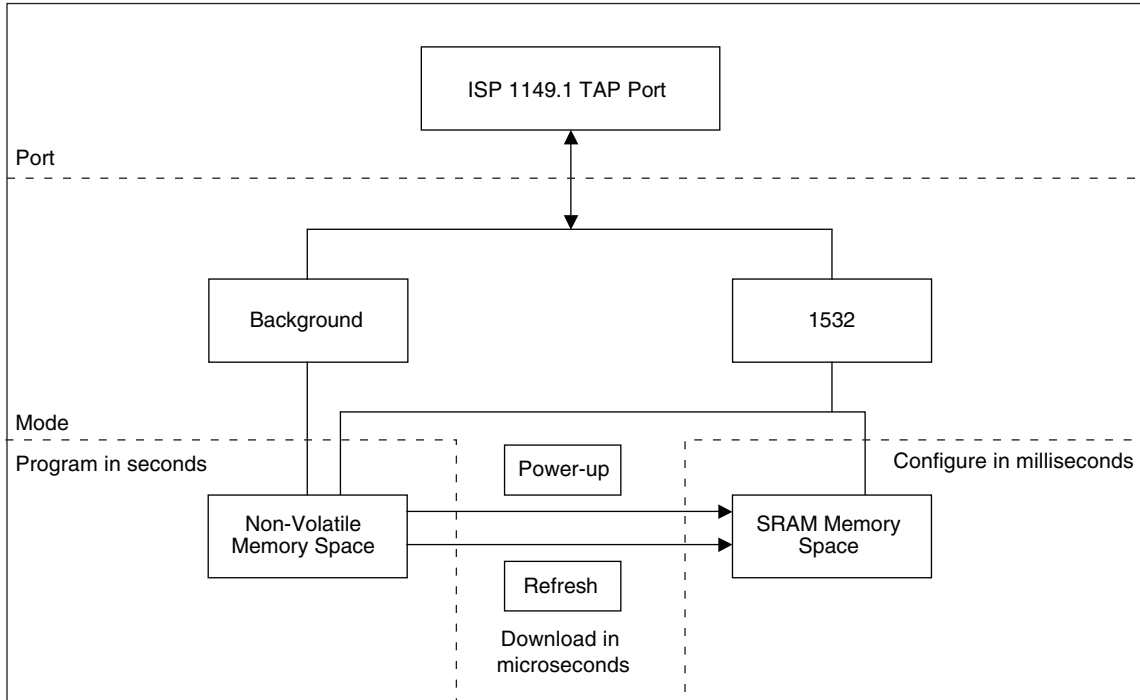
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, [Minimizing System Interruption During Configuration Using TransFR Technology](#) for details.

Security

The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

Figure 2-22. MachXO Configuration and Programming



Density Shifting

The MachXO family has been designed to enable density migration in the same package. Furthermore, the architecture ensures a high success rate when performing design migration from lower density parts to higher density parts. In many cases, it is also possible to shift a lower utilization design targeted for a high-density device to a lower density device. However, the exact details of the final resource utilization will impact the likely success in each case.

sysIO Differential Electrical Characteristics

LVDS

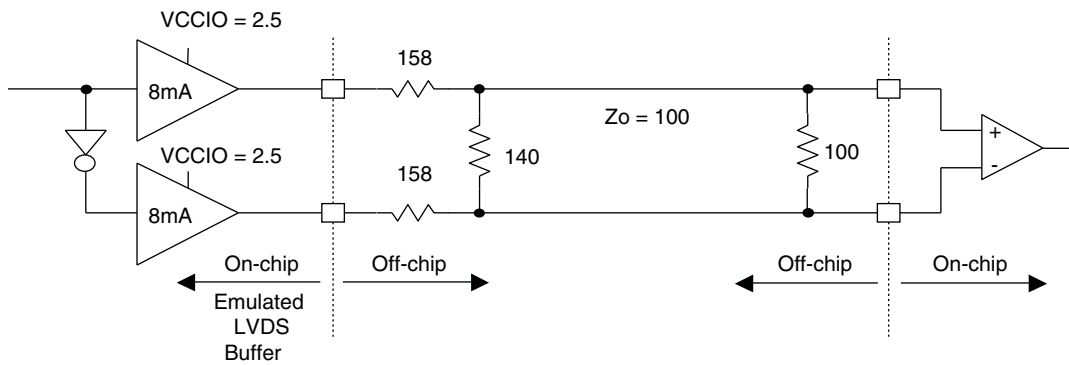
Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	$100\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		$200\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		$350\text{mV} \leq V_{THD}$	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on	—	—	+/-10	μA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	$R_T = 100 \text{ Ohm}$	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM}), R_T = 100 \text{ Ohm}$	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} - V_{OM})/2, R_T = 100 \text{ Ohm}$	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	$V_{OD} = 0\text{V}$ Driver outputs shorted	—	—	6	mA

LVDS Emulation

MachXO devices can support LVDS outputs via emulation (LVDS25E), in addition to the LVDS support that is available on-chip on certain devices. The output is emulated using complementary LVCMOS outputs in conjunction with resistors across the driver outputs on all devices. The scheme shown in Figure 3-1 is one possible solution for LVDS standard implementation. Resistor values in Figure 3-1 are industry standard values for 1% resistors.

Figure 3-1. LVDS Using External Resistors (LVDS25E)



Note: All resistors are $\pm 1\%$.

The LVDS differential input buffers are available on certain devices in the MachXO family.

MachXO Family Timing Adders^{1, 2, 3}

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25 ⁴	LVDS	0.44	0.53	0.61	ns
BLVDS25 ⁴	BLVDS	0.44	0.53	0.61	ns
LVPECL33 ⁴	LVPECL	0.42	0.50	0.59	ns
LVTTTL33	LVTTTL	0.01	0.01	0.01	ns
LVC MOS33	LVC MOS 3.3	0.01	0.01	0.01	ns
LVC MOS25	LVC MOS 2.5	0.00	0.00	0.00	ns
LVC MOS18	LVC MOS 1.8	0.07	0.08	0.10	ns
LVC MOS15	LVC MOS 1.5	0.14	0.17	0.19	ns
LVC MOS12	LVC MOS 1.2	0.40	0.48	0.56	ns
PCI33 ⁴	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25 ⁴	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTTL33_4mA	LVTTTL 4mA drive	0.04	0.04	0.05	ns
LVTTTL33_8mA	LVTTTL 8mA drive	0.06	0.07	0.08	ns
LVTTTL33_12mA	LVTTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTTL33_16mA	LVTTTL 16mA drive	0.50	0.60	0.70	ns
LVC MOS33_4mA	LVC MOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVC MOS33_8mA	LVC MOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVC MOS33_12mA	LVC MOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVC MOS33_14mA	LVC MOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVC MOS25_4mA	LVC MOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVC MOS25_8mA	LVC MOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVC MOS25_12mA	LVC MOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVC MOS25_14mA	LVC MOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVC MOS18_4mA	LVC MOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVC MOS18_8mA	LVC MOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVC MOS18_12mA	LVC MOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVC MOS18_14mA	LVC MOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVC MOS15_4mA	LVC MOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVC MOS15_8mA	LVC MOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVC MOS12_2mA	LVC MOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVC MOS12_6mA	LVC MOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33 ⁴	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.

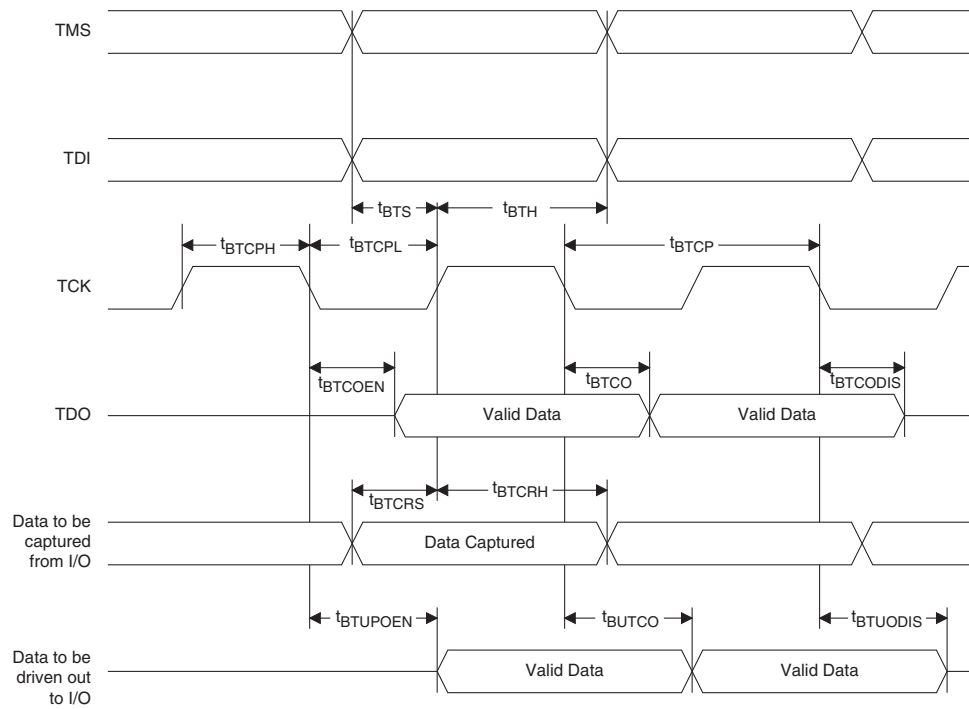
2. LVC MOS timing is measured with the load specified in Switching Test Conditions table.

3. All other standards tested according to the appropriate specifications.

4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

Rev. A 0.19

Figure 3-5. JTAG Port Timing Waveforms



Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number]_[A/B/C/D/E/F]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected. Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic. During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V _{CC}	—	VCC - The power supply pins for core logic. Dedicated pins.
V _{CCAUX}	—	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V _{CCIOx}	—	VCCIO - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN ¹	I	Sleep Mode pin - Active low sleep pin. ^b When this pin is held high, the device operates normally. ^b This pin has a weak internal pull-up, but when unused, an external pull-up to V _{CC} is recommended. When driven low, the device moves into Sleep mode after a specified time.
PLL and Clock Functions (Used as user programmable I/O pins when not used for PLL or clock pins)		
[LOC][0]_PLL[T, C]_IN	—	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
[LOC][0]_PLL[T, C]_FB	—	Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin -Test Data output pin used to shift data out of the device using 1149.1.

1. Applies to MachXO "C" devices only. NC for "E" devices.

LCMX0256 and LCMX0640 Logic Signal Connections: 100 TQFP

Pin Number	LCMX0256				LCMX0640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	1		T	PL2A	3		T
2	PL2B	1		C	PL2C	3		T
3	PL3A	1		T	PL2B	3		C
4	PL3B	1		C	PL2D	3		C
5	PL3C	1		T	PL3A	3		T
6	PL3D	1		C	PL3B	3		C
7	PL4A	1		T	PL3C	3		T
8	PL4B	1		C	PL3D	3		C
9	PL5A	1		T	PL4A	3		
10	VCCIO1	1			VCCIO3	3		
11	PL5B	1		C	PL4C	3		T
12	GNDIO1	1			GNDIO3	3		
13	PL5C	1		T	PL4D	3		C
14	PL5D	1	GSRN	C	PL5B	3	GSRN	
15	PL6A	1		T	PL7B	3		
16	PL6B	1	TSALL	C	PL8C	3	TSALL	T
17	PL7A	1		T	PL8D	3		C
18	PL7B	1		C	PL9A	3		
19	PL7C	1		T	PL9C	3		
20	PL7D	1		C	PL10A	3		
21	PL8A	1		T	PL10C	3		
22	PL8B	1		C	PL11A	3		
23	PL9A	1		T	PL11C	3		
24	VCCIO1	1			VCCIO3	3		
25	GNDIO1	1			GNDIO3	3		
26	TMS	1	TMS		TMS	2	TMS	
27	PL9B	1		C	PB2C	2		
28	TCK	1	TCK		TCK	2	TCK	
29	PB2A	1		T	VCCIO2	2		
30	PB2B	1		C	GNDIO2	2		
31	TDO	1	TDO		TDO	2	TDO	
32	PB2C	1		T	PB4C	2		
33	TDI	1	TDI		TDI	2	TDI	
34	PB2D	1		C	PB4E	2		
35	VCC	-			VCC	-		
36	PB3A	1	PCLK1_1**	T	PB5B	2	PCLK2_1**	
37	PB3B	1		C	PB5D	2		
38	PB3C	1	PCLK1_0**	T	PB6B	2	PCLK2_0**	
39	PB3D	1		C	PB6C	2		
40	GND	-			GND	-		
41	VCCIO1	1			VCCIO2	2		
42	GNDIO1	1			GNDIO2	2		

LCMX0256 and LCMX0640 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMX0256				LCMX0640			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
43	PB4A	1		T	PB8B	2		
44	PB4B	1		C	PB8C	2		T
45	PB4C	1		T	PB8D	2		C
46	PB4D	1		C	PB9A	2		
47	PB5A	1			PB9C	2		T
48*	SLEEPN	-	SLEEPN		SLEEPN	-	SLEEPN	
49	PB5C	1		T	PB9D	2		C
50	PB5D	1		C	PB9F	2		
51	PR9B	0		C	PR11D	1		C
52	PR9A	0		T	PR11B	1		C
53	PR8B	0		C	PR11C	1		T
54	PR8A	0		T	PR11A	1		T
55	PR7D	0		C	PR10D	1		C
56	PR7C	0		T	PR10C	1		T
57	PR7B	0		C	PR10B	1		C
58	PR7A	0		T	PR10A	1		T
59	PR6B	0		C	PR9D	1		
60	VCCIO0	0			VCCIO1	1		
61	PR6A	0		T	PR9B	1		
62	GNDIO0	0			GNDIO1	1		
63	PR5D	0		C	PR7B	1		
64	PR5C	0		T	PR6C	1		
65	PR5B	0		C	PR6B	1		
66	PR5A	0		T	PR5D	1		
67	PR4B	0		C	PR5B	1		
68	PR4A	0		T	PR4D	1		
69	PR3D	0		C	PR4B	1		
70	PR3C	0		T	PR3D	1		
71	PR3B	0		C	PR3B	1		
72	PR3A	0		T	PR2D	1		
73	PR2B	0		C	PR2B	1		
74	VCCIO0	0			VCCIO1	1		
75	GNDIO0	0			GNDIO1	1		
76	PR2A	0		T	PT9F	0		C
77	PT5C	0			PT9E	0		T
78	PT5B	0		C	PT9C	0		
79	PT5A	0		T	PT9A	0		
80	PT4F	0		C	VCCIO0	0		
81	PT4E	0		T	GNDIO0	0		
82	PT4D	0		C	PT7E	0		
83	PT4C	0		T	PT7A	0		
84	GND	-			GND	-		

LCMX01200 and LCMX02280 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	LCMX01200				LCMX02280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
82	PT9A	1			PT12C	1		T
83	GND	-			GND	-		
84	PT8B	1		C	PT11B	1		C
85	PT8A	1		T	PT11A	1		T
86	PT7D	1	PCLK1_1****		PT10B	1	PCLK1_1****	
87	PT6F	0	PCLK0_0****		PT9B	1	PCLK1_0****	
88	PT6D	0		C	PT8F	0		C
89	PT6C	0		T	PT8E	0		T
90	VCCAUX	-			VCCAUX	-		
91	VCC	-			VCC	-		
92	PT5B	0			PT6D	0		
93	PT4B	0			PT6F	0		
94	VCCIO0	0			VCCIO0	0		
95	PT3D	0		C	PT4B	0		C
96	PT3C	0		T	PT4A	0		T
97	PT3B	0			PT3B	0		
98	PT2B	0		C	PT2B	0		C
99	PT2A	0		T	PT2A	0		T
100**	GNDIO0 GNDIO7	-			GNDIO0 GNDIO7	-		

*Supports true LVDS outputs.

**Double bonded to the pin.

***NC for "E" devices.

****Primary clock inputs are single-ended.

LCMX0256 and LCMX0640 Logic Signal Connections: 100 csBGA

LCMX0256					LCMX0640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
B1	PL2A	1		T	B1	PL2A	3		T
C1	PL2B	1		C	C1	PL2C	3		T
D2	PL3A	1		T	D2	PL2B	3		C
D1	PL3B	1		C	D1	PL2D	3		C
C2	PL3C	1		T	C2	PL3A	3		T
E1	PL3D	1		C	E1	PL3B	3		C
E2	PL4A	1		T	E2	PL3C	3		T
F1	PL4B	1		C	F1	PL3D	3		C
F2	PL5A	1		T	F2	PL4A	3		
G2	PL5B	1		C	G2	PL4C	3		T
H1	GNDIO1	1			H1	GNDIO3	3		
H2	PL5C	1		T	H2	PL4D	3		C
J1	PL5D	1	GSRN	C	J1	PL5B	3	GSRN	
J2	PL6A	1		T	J2	PL7B	3		
K1	PL6B	1	TSALL	C	K1	PL8C	3	TSALL	T
K2	PL7A	1		T	K2	PL8D	3		C
L1	PL7B	1		C	L1	PL9A	3		
L2	PL7C	1		T	L2	PL9C	3		
M1	PL7D	1		C	M1	PL10A	3		
M2	PL8A	1		T	M2	PL10C	3		
N1	PL8B	1		C	N1	PL11A	3		
M3	PL9A	1		T	M3	PL11C	3		
N2	GNDIO1	1			N2	GNDIO3	3		
P2	TMS	1	TMS		P2	TMS	2	TMS	
P3	PL9B	1		C	P3	PB2C	2		
N4	TCK	1	TCK		N4	TCK	2	TCK	
P4	PB2A	1		T	P4	VCCIO2	2		
N3	PB2B	1		C	N3	GNDIO2	2		
P5	TDO	1	TDO		P5	TDO	2	TDO	
N5	PB2C	1		T	N5	PB4C	2		
P6	TDI	1	TDI		P6	TDI	2	TDI	
N6	PB2D	1		C	N6	PB4E	2		
P7	VCC	-			P7	VCC	-		
N7	PB3A	1	PCLK1_1**	T	N7	PB5B	2	PCLK2_1**	
P8	PB3B	1		C	P8	PB5D	2		
N8	PB3C	1	PCLK1_0**	T	N8	PB6B	2	PCLK2_0**	
P9	PB3D	1		C	P9	PB6C	2		
N10	GNDIO1	1			N10	GNDIO2	2		
P11	PB4A	1		T	P11	PB8B	2		
N11	PB4B	1		C	N11	PB8C	2		T
P12	PB4C	1		T	P12	PB8D	2		C
N12	PB4D	1		C	N12	PB9A	2		

LCMX0256 and LCMX0640 Logic Signal Connections: 100 csBGA (Cont.)

LCMX0256					LCMX0640				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
P13	PB5A	1			P13	PB9C	2		T
M12*	SLEEPN	-	SLEEPN		M12*	SLEEPN	-	SLEEPN	
P14	PB5C	1		T	P14	PB9D	2		C
N13	PB5D	1		C	N13	PB9F	2		
N14	PR9B	0		C	N14	PR11D	1		C
M14	PR9A	0		T	M14	PR11B	1		C
L13	PR8B	0		C	L13	PR11C	1		T
L14	PR8A	0		T	L14	PR11A	1		T
M13	PR7D	0		C	M13	PR10D	1		C
K14	PR7C	0		T	K14	PR10C	1		T
K13	PR7B	0		C	K13	PR10B	1		C
J14	PR7A	0		T	J14	PR10A	1		T
J13	PR6B	0		C	J13	PR9D	1		
H13	PR6A	0		T	H13	PR9B	1		
G14	GNDIO0	0			G14	GNDIO1	1		
G13	PR5D	0		C	G13	PR7B	1		
F14	PR5C	0		T	F14	PR6C	1		
F13	PR5B	0		C	F13	PR6B	1		
E14	PR5A	0		T	E14	PR5D	1		
E13	PR4B	0		C	E13	PR5B	1		
D14	PR4A	0		T	D14	PR4D	1		
D13	PR3D	0		C	D13	PR4B	1		
C14	PR3C	0		T	C14	PR3D	1		
C13	PR3B	0		C	C13	PR3B	1		
B14	PR3A	0		T	B14	PR2D	1		
C12	PR2B	0		C	C12	PR2B	1		
B13	GNDIO0	0			B13	GNDIO1	1		
A13	PR2A	0		T	A13	PT9F	0		C
A12	PT5C	0			A12	PT9E	0		T
B11	PT5B	0		C	B11	PT9C	0		
A11	PT5A	0		T	A11	PT9A	0		
B12	PT4F	0		C	B12	VCCIO0	0		
A10	PT4E	0		T	A10	GNDIO0	0		
B10	PT4D	0		C	B10	PT7E	0		
A9	PT4C	0		T	A9	PT7A	0		
A8	PT4B	0	PCLK0_1**	C	A8	PT6B	0	PCLK0_1**	
B8	PT4A	0	PCLK0_0**	T	B8	PT5B	0	PCLK0_0**	C
A7	PT3D	0		C	A7	PT5A	0		T
B7	VCCAUX	-			B7	VCCAUX	-		
A6	PT3C	0		T	A6	PT4F	0		
B6	VCC	-			B6	VCC	-		
A5	PT3B	0		C	A5	PT3F	0		

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 144 TQFP

Pin Number	LCMXO640				LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	3		T	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2C	3		T	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL2B	3		C	PL3A	7		T*	PL3A	7		T*
4	PL3A	3		T	PL3B	7		C*	PL3B	7		C*
5	PL2D	3		C	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
6	PL3B	3		C	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
7	PL3C	3		T	PL4A	7		T*	PL4A	7		T*
8	PL3D	3		C	PL4B	7		C*	PL4B	7		C*
9	PL4A	3			PL4C	7			PL4C	7		
10	VCCIO3	3			VCCIO7	7			VCCIO7	7		
11	GNDIO3	3			GNDIO7	7			GNDIO7	7		
12	PL4D	3			PL5C	7			PL6C	7		
13	PL5A	3		T	PL6A	7		T*	PL7A	7		T*
14	PL5B	3	GSRN	C	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
15	PL5D	3			PL6D	7			PL7D	7		
16	GND	-			GND	-			GND	-		
17	PL6C	3		T	PL7C	7		T	PL9C	7		T
18	PL6D	3		C	PL7D	7		C	PL9D	7		C
19	PL7A	3		T	PL10A	6		T*	PL13A	6		T*
20	PL7B	3		C	PL10B	6		C*	PL13B	6		C*
21	VCC	-			VCC	-			VCC	-		
22	PL8A	3		T	PL11A	6		T*	PL13D	6		
23	PL8B	3		C	PL11B	6		C*	PL14D	6		C
24	PL8C	3	TSALL		PL11C	6	TSALL		PL14C	6	TSALL	T
25	PL9C	3		T	PL12B	6			PL15B	6		
26	VCCIO3	3			VCCIO6	6			VCCIO6	6		
27	GNDIO3	3			GNDIO6	6			GNDIO6	6		
28	PL9D	3		C	PL13D	6			PL16D	6		
29	PL10A	3		T	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
30	PL10B	3		C	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
31	PL10C	3		T	PL14C	6		T	PL17C	6		T
32	PL11A	3		T	PL14D	6		C	PL17D	6		C
33	PL10D	3		C	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
34	PL11C	3		T	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
35	PL11B	3		C	PL16A	6		T	PL19A	6		T
36	PL11D	3		C	PL16B	6		C	PL19B	6		C
37	GNDIO2	2			GNDIO5	5			GNDIO5	5		
38	VCCIO2	2			VCCIO5	5			VCCIO5	5		
39	TMS	2	TMS		TMS	5	TMS		TMS	5	TMS	
40	PB2C	2			PB2C	5		T	PB2A	5		T
41	PB3A	2		T	PB2D	5		C	PB2B	5		C
42	TCK	2	TCK		TCK	5	TCK		TCK	5	TCK	
43	PB3B	2		C	PB3A	5		T	PB3A	5		T
44	PB3C	2		T	PB3B	5		C	PB3B	5		C
45	PB3D	2		C	PB4A	5		T	PB4A	5		T
46	PB4A	2		T	PB4B	5		C	PB4B	5		C
47	TDO	2	TDO		TDO	5	TDO		TDO	5	TDO	
48	PB4B	2		C	PB4D	5			PB4D	5		
49	PB4C	2		T	PB5A	5		T	PB5A	5		T
50	PB4D	2		C	PB5B	5		C	PB5B	5		C

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
D3	NC				D3	PT2C	0		T	D3	PT3C	0		T
A3	PT2B	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2A	0		T	A2	PT3A	0		T	A2	PT3A	0		T
B3	NC				B3	PT2B	0		C	B3	PT2D	0		C
B2	NC				B2	PT2A	0		T	B2	PT2C	0		T
VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0			VCCIO0	VCCIO0	0		
GND	GNDIO0	0			GND	GNDIO0	0			GND	GNDIO0	0		
A1	GND	-			A1	GND	-			A1	GND	-		
A16	GND	-			A16	GND	-			A16	GND	-		
F11	GND	-			F11	GND	-			F11	GND	-		
G8	GND	-			G8	GND	-			G8	GND	-		
G9	GND	-			G9	GND	-			G9	GND	-		
H7	GND	-			H7	GND	-			H7	GND	-		
H8	GND	-			H8	GND	-			H8	GND	-		
H9	GND	-			H9	GND	-			H9	GND	-		
H10	GND	-			H10	GND	-			H10	GND	-		
J7	GND	-			J7	GND	-			J7	GND	-		
J8	GND	-			J8	GND	-			J8	GND	-		
J9	GND	-			J9	GND	-			J9	GND	-		
J10	GND	-			J10	GND	-			J10	GND	-		
K8	GND	-			K8	GND	-			K8	GND	-		
K9	GND	-			K9	GND	-			K9	GND	-		
L6	GND	-			L6	GND	-			L6	GND	-		
T1	GND	-			T1	GND	-			T1	GND	-		
T16	GND	-			T16	GND	-			T16	GND	-		
G7	VCC	-			G7	VCC	-			G7	VCC	-		
G10	VCC	-			G10	VCC	-			G10	VCC	-		
K7	VCC	-			K7	VCC	-			K7	VCC	-		
K10	VCC	-			K10	VCC	-			K10	VCC	-		
H6	VCCIO3	3			H6	VCCIO7	7			H6	VCCIO7	7		
G6	VCCIO3	3			G6	VCCIO7	7			G6	VCCIO7	7		
K6	VCCIO3	3			K6	VCCIO6	6			K6	VCCIO6	6		
J6	VCCIO3	3			J6	VCCIO6	6			J6	VCCIO6	6		
L8	VCCIO2	2			L8	VCCIO5	5			L8	VCCIO5	5		
L7	VCCIO2	2			L7	VCCIO5	5			L7	VCCIO5	5		
L9	VCCIO2	2			L9	VCCIO4	4			L9	VCCIO4	4		
L10	VCCIO2	2			L10	VCCIO4	4			L10	VCCIO4	4		
K11	VCCIO1	1			K11	VCCIO3	3			K11	VCCIO3	3		
J11	VCCIO1	1			J11	VCCIO3	3			J11	VCCIO3	3		
H11	VCCIO1	1			H11	VCCIO2	2			H11	VCCIO2	2		
G11	VCCIO1	1			G11	VCCIO2	2			G11	VCCIO2	2		
F9	VCCIO0	0			F9	VCCIO1	1			F9	VCCIO1	1		
F10	VCCIO0	0			F10	VCCIO1	1			F10	VCCIO1	1		
F8	VCCIO0	0			F8	VCCIO0	0			F8	VCCIO0	0		
F7	VCCIO0	0			F7	VCCIO0	0			F7	VCCIO0	0		

* Supports true LVDS outputs.

** NC for "E" devices.

*** Primary clock inputs are single-ended.

LCMX02280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMX02280				
Ball Number	Ball Function	Bank	Dual Function	Differential
F16	GND	-		
H10	GND	-		
H11	GND	-		
H8	GND	-		
H9	GND	-		
J10	GND	-		
J11	GND	-		
J4	GND	-		
J8	GND	-		
J9	GND	-		
K10	GND	-		
K11	GND	-		
K17	GND	-		
K8	GND	-		
K9	GND	-		
L10	GND	-		
L11	GND	-		
L8	GND	-		
L9	GND	-		
N2	GND	-		
P14	GND	-		
P5	GND	-		
R7	GND	-		
F14	VCC	-		
G11	VCC	-		
G9	VCC	-		
H7	VCC	-		
L7	VCC	-		
M9	VCC	-		
H6	VCCIO7	7		
J7	VCCIO7	7		
M7	VCCIO6	6		
K7	VCCIO6	6		
M8	VCCIO5	5		
R9	VCCIO5	5		
M12	VCCIO4	4		
M11	VCCIO4	4		
L12	VCCIO3	3		
K12	VCCIO3	3		
J12	VCCIO2	2		
H12	VCCIO2	2		
G12	VCCIO1	1		
G10	VCCIO1	1		

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential
G8	VCCIO0	0		
G7	VCCIO0	0		

* Supports true LVDS outputs.

** NC for "E" devices.

*** Primary clock inputs are single-ended.

Date	Version	Section	Change Summary
November 2006	02.3	DC and Switching Characteristics	Corrections to MachXO “C” Sleep Mode Timing table - value for $t_{WSLEEPN}$ (400ns) changed from max. to min. Value for t_{WAWAKE} (100ns) changed from min. to max.
			Added Flash Download Time table.
December 2006	02.4	Architecture	EBR Asynchronous Reset section added.
		Pinout Information	Power Supply and NC table; Pin/Ball orientation footnotes added.
February 2007	02.5	Architecture	Updated EBR Asynchronous Reset section.
August 2007	02.6	DC and Switching Characteristics	Updated sysIO Single-Ended DC Electrical Characteristics table.
November 2007	02.7	DC and Switching Characteristics	Added JTAG Port Timing Waveforms diagram.
		Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
June 2009	02.8	Introduction	Added 0.8-mm 256-pin caBGA package to MachXO Family Selection Guide table.
		Pinout Information	Added Logic Signal Connections table for 0.8-mm 256-pin caBGA package.
		Ordering Information	Updated Part Number Description diagram and Ordering Part Number tables with 0.8-mm 256-pin caBGA package information.
July 2010	02.9	DC and Switching Characteristics	Updated sysCLOCK PLL Timing table.
June 2013	03.0	All	Updated document with new corporate logo.
		Architecture	Architecture Overview – Added information on the state of the register on power up and after configuration.
		DC and Switching Characteristics	MachXO1200 and MachXO2280 Hot Socketing Specifications table – Removed footnote 4.
			Added MachXO Programming/Erase Specifications table.